External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01987	0.03	1.4568
	Copper alloy	Iron (Fe)	7439-89-6	0.06625	0.1	4.856
	Copper alloy	Copper (Cu)	7440-50-8	66.16253	99.87	4849.6872
			Subtotal	66.24865	100	4856
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.32606	4.0	97.2
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.97274	15.0	364.5
	Filler	Silica fused	60676-86-0	24.53219	74.0	1798.2
	Flame retardant	Metal hydroxide		2.32061	7.0	170.1
			Subtotal	33.1516	100	2430
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.40928	100.0	30
			Subtotal	0.40928	100	30
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.03684	100.0	2.7
			Subtotal	0.03684	100	2.7
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.03547	65.0	2.6
	Lead alloy	Silver (Ag)	7440-22-4	0.01364	25.0	1
	Lead alloy	Antimony (Sb)	7440-36-0	0.00546	10.0	0.4
			Subtotal	0.05457	100	4
Die		Silicon Carbide (SiC)	409-21-2	0.09905	100.0	7.26
			Subtotal	0.09905	100	7.26
			Total	99.99999	100	7329.96

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